



DKRED 2 layer stackup and board documentation

Layer	Base CU + Plt	Thick	Type	Stackup	Subs	Imp	Material	Dk	Df
Silkscreen		0.00					Taiyo-SS - White	1.00	
Soldermask		0.60					Taiyo-SM - Red	3.90	0.033
Lyr1	0.5oz / Std	1.80	S						
Core		57.80					370HR - 59.0mils	4.04	0.021
Lyr2	0.5oz / Std	1.80	S						
Soldermask		0.60					Taiyo-SM - Red	3.90	0.033
Silkscreen		0.00					Taiyo-SS - White	1.00	

Required thickness

Type	Req. thick	Tol% +	Tol% -	Act. thick	Measured
Overall	62.0	10.0	10.0	62.6	
Over lamination	58.4	10.0	10.0	59.0	
Over laminate	57.2	10.0	10.0	57.8	
Over metal	60.8	10.0	10.0	61.4	

Bill of materials

Material	Qty/Panel	Total Qty
59.0mils H/H core	1	1
	1	1

Common specs

Spec	-	Value
Manufactured in the United States	-	Yes
RoHS Compliant	-	Yes
PCB Finish	-	ENIG

Updated March 11, 2025



Material specs

Spec	Value
material	FR4 Tg 170-180
Board thickness	62 mils
Soldermask color	RED
Maximum board size	10in x 10in
Minimum Board size	1in x 1in

Copper Specifications

Spec	Value
Copper layers	2
Copper weight	1oz
Trace spacing	5 mils
Trace width	5 mils
Plating thickness	1 mil

Drill Specifications

Spec	Value
Minimum drill size	8 mils
Minimum slot size	No slots
Castellations	None
Maximum drill size	None

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